

SPECIFICATION AMENDMENTS

Please replace the paragraph beginning at page 1, line 5, with the following rewritten paragraph:

-- This application claims the priority benefit of Japanese Patent Application No. 10-354757, filed December 14, 1998, the entire subject matter of which is incorporated herein of reference. This application is a divisional application of applicant's application Serial No. 10/289,358, filed November 7, 2002, which is division of applicant's application Serial No. 10/022, 285, filed 12/20/01, which is division of applicant's application Serial No. 09/450,504, filed November 30, 1999, which is now patented, No. 6,420, 658. --

Please replace the paragraph beginning at page 3, line 3, with the following rewritten paragraph:

--The invention will be more particularly described with reference to the accompanying drawings in which:

Fig. 1(a) is a plan view of a module circuit board of the first embodiment of the invention,

Fig. 1(b) is an enlarged sectional view taken along line I-I' shown in Fig. 1(a),

Fig. 2(a) is a plan view of a module circuit board of the second embodiment of the invention,

Fig. 2(b) is an enlarged sectional view taken along line II-II' shown in Fig. 2(a),

Fig. 3(a) is a plan view of a module circuit board of the third embodiment of the invention,

Fig. 3(b) is an enlarged sectional view taken along line III-III' shown in Fig. 3(a),

Fig. 4(a) is a plan view of a module circuit board of the fourth embodiment of the invention,

Fig. 4(b) is an enlarged sectional view taken along line IV-IV' shown in Fig. 4(a),

Fig. 5(a) is a plan view of a module circuit board of the fifth embodiment of the invention,

Fig. 5(b) is an enlarged sectional view taken along line V-V' shown in Fig. 5(a),

Fig. 6(a) is a plan view of a module circuit board of the sixth embodiment of the invention, and

Fig. 6(b) is an enlarged sectional view taken along line VI-VI' shown in Fig. 6(a). --